Amendments To The Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of claims:

- 1. (Presently Amended) A flame retarded epoxy resin composition <u>coated on a substrate to form a dielectric material for a build-up process</u>, which comprises:
 - (A) at least one type of epoxy resin; and
- (B) a phosphorus-and-nitrogen-containing heterocyclic compound, said compound having a moiety which ean-is capable of reacting with anthe epoxy group of the epoxy resin, is useful as a hardening agent for the epoxy resin, and having a structure as shown by formula (I):

$$(NH_2)_{2-m}$$

$$N = P \quad 1_n \quad (I)$$

wherein m is an integer of from 0 to 2, n is an integer of from 3 to 7, but at least one occurrence of m in formula (I) is not 2.

- 2. (Presently Amended) The A flame retarded epoxy resin composition coated on a substrate to form a dielectric material for a build-up process which comprises according to claim 1, further comprising:
 - (A) at least one type of epoxy resin; and

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(B) a phosphorus and nitrogen containing heterocyclic compound, said compound having a moiety which can react with the epoxy group of the epoxy resin, useful as a hardening agent for the epoxy resin, and having a structure as shown by formula (I):

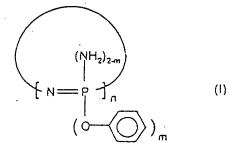
$$\begin{array}{c|c} & & & \\ & & \\ & & & \\ & & & \\ & & & \\ & & \\ & & & \\ & & & \\ & & & \\ & & & \\ & & & \\ & & & \\$$

wherein m is an integer of from 0 to 2, n is an integer of from 3 to 7, but at least one m is not 2; and

- (C) a hardening agent, which does not contain phosphorus;
- and selectively added:
- (D) a hardening promoter;
- (E) a solvent; and, additionally,
- (F) additives.
- 3-20. (Cancelled).
- 21. (Presently Amended) The flame retarded epoxy resin composition <u>coated on a substrate to form a dielectric material for a build-up process</u> according to claim <u>191</u>, wherein the substrate used for making dielectric materials for the build-up process is copper foil or releasing film.

22-23. (Cancelled).

- 24. (New) The flame retarded epoxy resin composition coated on a substrate to form a dielectric material for a build-up process according to claim 2, wherein the substrate used for making dielectric materials for the build-up process is copper foil or releasing film.
- 25. (New) A prepreg comprising a reinforced substrate and a flame retarded epoxy resin composition, wherein the flame retarded epoxy resin composition comprises:
 - (A) at least one epoxy resin; and
- (B) a phosphorus-and-nitrogen-containing heterocyclic compound, said compound having a moiety which is capable of reacting with an epoxy group of the epoxy resin, is useful as a hardening agent for the epoxy resin, and having a structure as shown by formula (I):



wherein m is an integer of from 0 to 2, n is an integer of from 3 to 7, but at least one occurrence of m in formula (I) is not 2.

- 26. (New) The prepreg of claim 25, wherein the flame retarded epoxy resin composition further comprises (C) a hardening agent, which does not contain phosphorus.
- 27. (new) The prepreg of claim 25, wherein the prepreg is laminated to form a laminate or laminated plate having flame retardancy and high heat resistance.
- 28. (new) The prepreg of claim 27, wherein the laminated prepreg further comprises a copper foil layer and is suitable for use in manufacturing of printed circuit boards.